Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

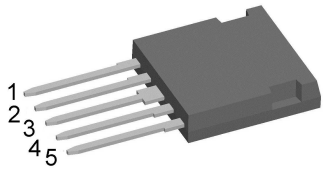
Standard Rectifier

1~ Rectifier		
V_{RRM}	=	1200
I_{DAV}	=	40
I_{FSM}	=	300

1~ Rectifier Bridge

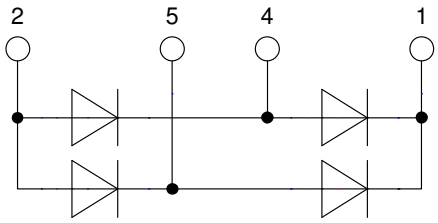
Part number

FBO40-12N



Backside: isolated

E72873



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

Applications:

- Diode Bridge for main rectification

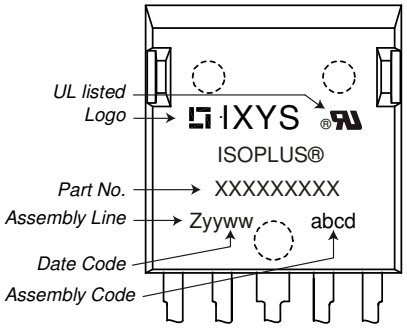
Package: i4-Pac

- Isolation Voltage: 3000 V~
- Industry convenient outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Soldering pins for PCB mounting
- Backside: DCB ceramic
- Reduced weight
- Advanced power cycling

Rectifier				Ratings			
Symbol	**Definition**	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
V_{RSM}	*max. non-repetitive reverse blocking voltage*		T_{VJ} = 25°C			1300	V
V_{RRM}	*max. repetitive reverse blocking voltage*		T_{VJ} = 25°C			1200	V
I_R	*reverse current*	V_R = 1200 V	T_{VJ} = 25°C			40	µA
		V_R = 1200 V	T_{VJ} = 150°C			1.5	mA
V_F	*forward voltage drop*	I_F = 20 A	T_{VJ} = 25°C			1.17	V
		I_F = 40 A				1.38	V
		I_F = 20 A	T_{VJ} = 150°C			1.09	V
		I_F = 40 A				1.37	V
I_{DAV}	*bridge output current*	T_C = 130°C	T_{VJ} = 175°C			40	A
		rectangular d = 0.5					
V_{F0}	*threshold voltage* } *for power loss calculation only*		T_{VJ} = 175°C			0.79	V
r_F	*slope resistance* }					14	mΩ
R_{thJC}	*thermal resistance junction to case*					1.5	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.20		K/W
P_{tot}	*total power dissipation*		T_C = 25°C			100	W
I_{FSM}	*max. forward surge current*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			300	A
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			325	A
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			255	A
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			275	A
I^2t	*value for fusing*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			450	A^2s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			440	A^2s
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			325	A^2s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			315	A^2s
C_J	*junction capacitance*	V_R = 400 V; f = 1 MHz	T_{VJ} = 25°C		4		pF

Package i4-Pac				Ratings			
Symbol	**Definition**	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
I_{RMS}	*RMS current*	per terminal				35	A
T_{VJ}	*virtual junction temperature*			-55		175	°C
T_{op}	*operation temperature*			-55		150	°C
T_{stg}	*storage temperature*			-55		150	°C
Weight					9		g
F_C	*mounting force with clip*			20		120	N
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*		*terminal to terminal*	1.7			mm
$d_{Spb/Apb}$			*terminal to backside*	5.1			mm
V_{ISOL}	*isolation voltage*	t = 1 second	50/60 Hz, RMS; I_{ISOL} ≤ 1 mA	3000			V
		t = 1 minute		2500			V

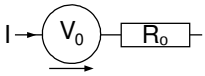
Product Marking



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	FBO40-12N	FBO40-12N	Tube	25	492256

Equivalent Circuits for Simulation

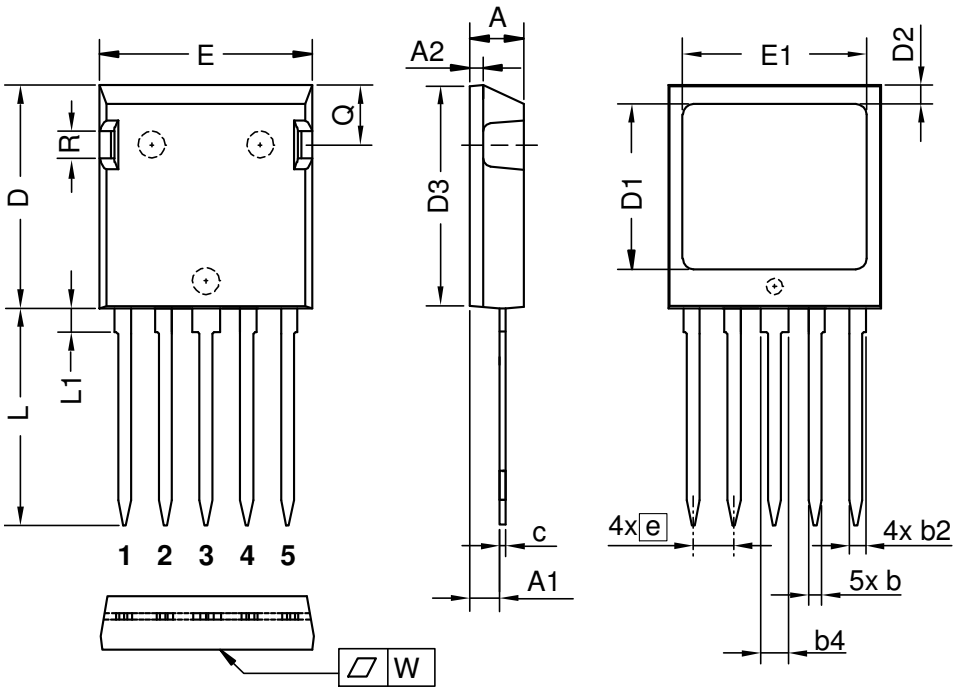
** on die level* T_{VJ} = 175 °C



Rectifier

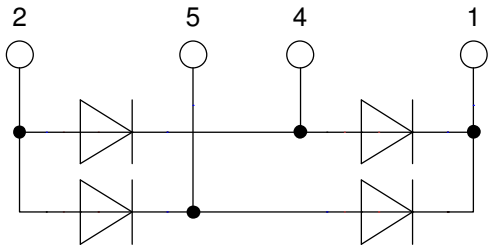
$V_{0\,max}$	*threshold voltage*	0.79	V
$R_{0\,max}$	*slope resistance **	12	mΩ

Outlines i4-Pac



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.83	5.21	0.190	0.205
A1	2.59	3.00	0.102	0.118
A2	1.17	2.16	0.046	0.085
b	1.14	1.40	0.045	0.055
b2	1.47	1.73	0.058	0.068
b4	2.54	2.79	0.100	0.110
c	0.51	0.74	0.020	0.029
D	20.80	21.34	0.819	0.840
D1	14.99	15.75	0.590	0.620
D2	1.65	2.03	0.065	0.080
D3	20.30	20.70	0.799	0.815
E	19.56	20.29	0.770	0.799
E1	16.76	17.53	0.660	0.690
e	3.81 BSC		0.150 BSC	
L	19.81	21.34	0.780	0.840
L1	2.11	2.59	0.083	0.102
Q	5.33	6.20	0.210	0.244
R	2.54	4.57	0.100	0.180
W	-	0.10	-	0.004

Die konvexe Form des Substrates ist typ. < 0.05 mm über der Kunststoffoberfläche der Bauteilunterseite
The convexbow of substrate is typ. < 0.05 mm over plastic surface level ofdevice bottom side



Rectifier

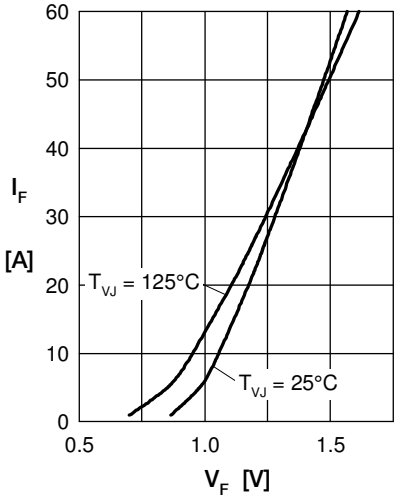


Fig. 1 Forward current versus voltage drop per diode

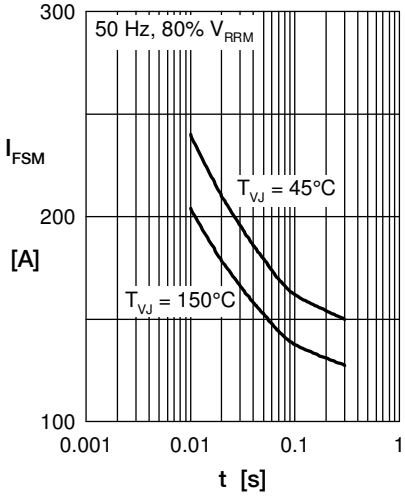


Fig. 2 Surge overload current

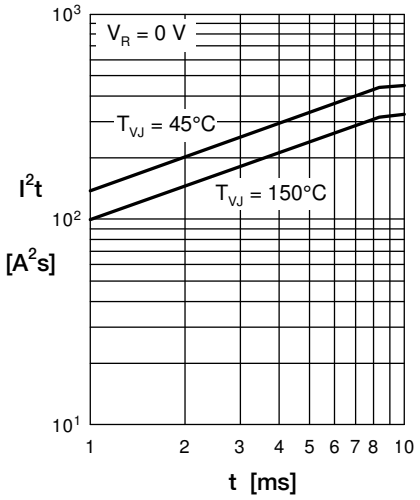


Fig. 3 I^2t versus time per diode

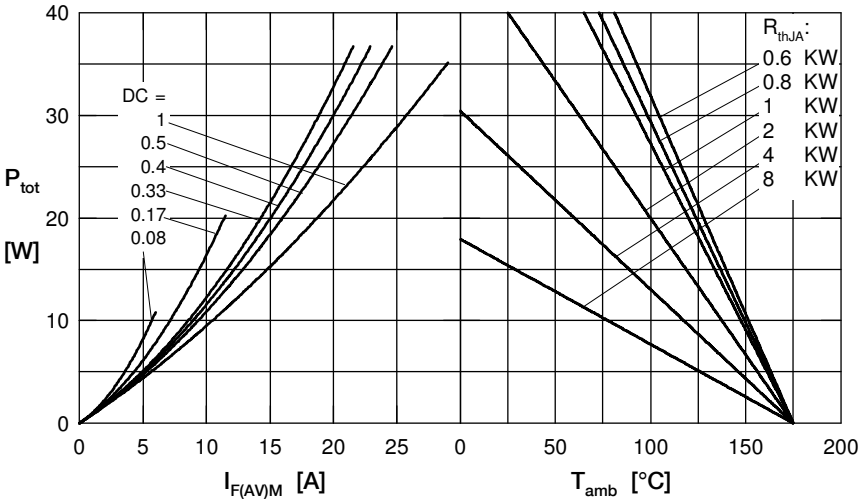


Fig. 4 Power dissipation vs. direct output current and ambient temperature

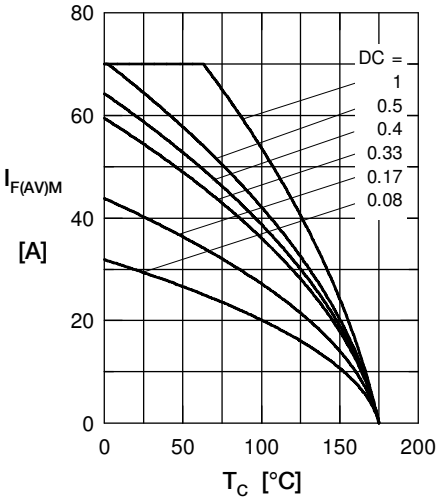


Fig. 5 Max. forward current vs. case temperature

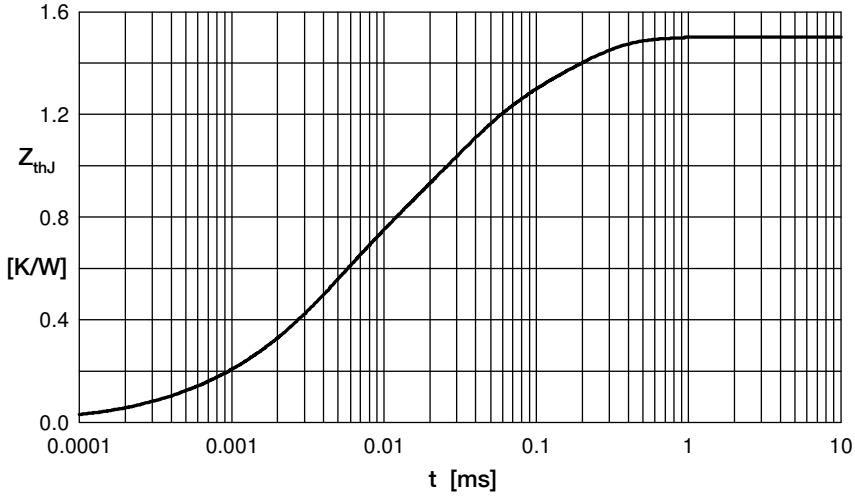


Fig. 6 Transient thermal impedance junction to case

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.06075	0.0004
2	0.183	0.00256
3	0.3405	0.0045
4	0.543	0.0242
5	0.3728	0.15